



Serial No. 09/295,709

IN THE SPECIFICATION:

On page 2, line 3, insert the following heading and paragraph:

-- CROSS-REFERENCE TO RELATED APPLICATION

B<sup>1</sup>  
This application is a divisional of application Serial No. 08/709,182, filed September 6, 1996, now U.S. Patent 6,083,768, issued July 4, 2000. --

IN THE CLAIMS:

Please amend claims 7, 8, 13 - 16, and 21 as follows:

SP  
D<sub>1</sub>  
7 (Amended) A semiconductor substrate [having] including at least one adhesive patch comprised of a viscous adhesive material, the at least one adhesive patch including a first surface adjacent said semiconductor substrate and a second, smaller surface opposite said first surface exhibiting a generally planar portion over a substantial portion thereof, said semiconductor substrate including said at least one adhesive patch formed by:  
providing a semiconductor substrate;  
[depositing an] dispensing a viscous adhesive material on said semiconductor substrate; and  
inverting said semiconductor substrate without effecting substantial lateral confinement of said adhesive material and maintaining said semiconductor substrate in an inverted position at least until said viscous adhesive material [obtains] sufficiently stabilizes so as to exhibit a desired stable shape and a lateral boundary [definition of said deposited adhesive material] defining sizes of said first and second surfaces of said at least one adhesive patch and wherein at least a substantial portion of said second, smaller surface of said adhesive patch exhibits a generally planar configuration and said size of said second, smaller surface is smaller than said size of said first surface.

OK